



(2.00 mm) .0787"

HDAF-15-18.0-S-13-2

HDAF-23-08.0-S-13-2

HDAF SERIES

RUGGED ELEVATED HIGH-DENSITY ARRAY

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HDAF

Insulator Material:

Black LCP

Contact Material:

Copper Alloy

Plating:

Au or Sn over 50 μ " (1.27 μ m) Ni

Operating Temp Range:

-55 °C to +125 °C

Current Rating:

1.8 A per pin (6 adjacent pins powered)

Working Voltage:

230 VAC/325 VDC

Mated Cycles:

100

RoHS Compliant:

Yes

Lead-Free Solderable:

Yes

Mates with:
HDAM

Intermateable with
Molex HD Mezz

299, 195
and 143 pins

Elevated
stack heights
of 20 mm, 25 mm,
30 mm and 35 mm

Open-pin-field for
Single-Ended
or Differential Pair
configurations

Lead-Free
Solder
Charge

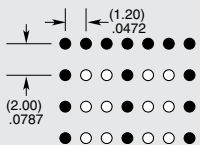
RECOGNITIONS

For complete scope of
recognitions see
www.samtec.com/quality



FILE NO. E111594

DIFFERENTIAL APPLICATIONS



ARRAY	PAIR COUNT*
11x13	44
15x13	60
23x13	92

*2:1 S:G Ratio

ALSO AVAILABLE

Contact Samtec

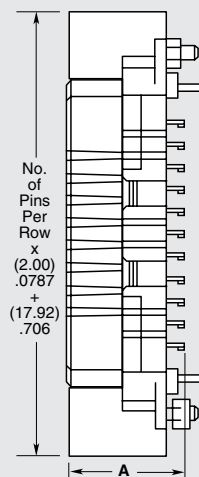
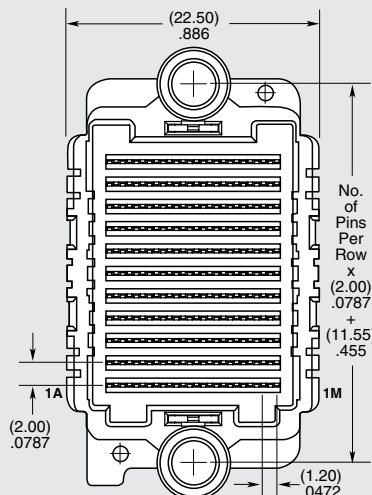
- Tin-Lead Solder Charge
- Other platings

Notes:

HD Mezz is a trademark of
Molex Incorporated

Some lengths, styles and
options are non-standard,
non-returnable.

HDAF	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	13	SOLDER TYPE	OPTION	PACKAGING
	-11, -15, -23	Specify LEAD STYLE from chart	-S = 30 μ " (0.76 μ m) Gold on contact area, Matte Tin on tails and guide pins	-2 = Lead-Free Tin Alloy 95.5% Sn/ 3.8% Ag/0.7% Cu Solder Charge	-P = Pick & Place Pad		Leave blank for tray packaging -TR = Tape & Reel -FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)



LEAD STYLE	A
-08.0	(10.51) .414
-18.0	(20.51) .807